heat dissipation significantly. If further thermal improvements are needed, double sided or multilayer PC boards with large copper areas should be considered. In order to achieve the best thermal performance, it is highly recommended to use wide copper traces as well as large areas of copper in the printed circuit board layout. The only exception to this is the OUTPUT (switch) pin, which should not have large areas of copper (see page 8 'PCB Layout Guideline').

Thermal Analysis and Design

The following procedure must be performed to determine whether or not a heatsink will be required. First determine:

1. $P_{D(max)}$ maximum regulator power dissipation in the application.
2. $T_{A(max)}$ maximum ambient temperature in the application.
3. $T_{J(max)}$ maximum allowed junction temperature (125°C for the LM2596). For a conservative design, the maximum junction temperature should not exceed 110°C to assure safe operation. For every additional +10°C temperature rise that the junction must withstand, the estimated operating lifetime of the component is halved.
4. $R_{\theta JC}$ package thermal resistance junction−case.
5. $R_{\theta JA}$ package thermal resistance junction−ambient.

(Refer to Maximum Ratings on page 2 of this data sheet or $R_{\theta JC}$ and $R_{\theta JA}$ values).

The following formula is to calculate the approximate total power dissipated by the LM2596:

$$P_D = (V_{in} \times I_Q) + d \times I_{Load} \times V_{sat}$$

where d is the duty cycle and for buck converter

$$d = \frac{t_{on}}{T} = \frac{V_O}{V_{in}},$$

I_Q (quiescent current) and V_{sat} can be found in the LM2596 data sheet,
V_{in} is minimum input voltage applied,
V_O is the regulator output voltage,
I_{Load} is the load current.

The dynamic switching losses during turn−on and turn−off can be neglected if proper type catch diode is used.

Packages Not on a Heatsink (Free−Standing)

For a free−standing application when no heatsink is used, the junction temperature can be determined by the following expression:

$$T_J = (R_{\theta JA})(P_D) + T_A$$

where $(R_{\theta JA})(P_D)$ represents the junction temperature rise caused by the dissipated power and T_A is the maximum ambient temperature.

Packages on a Heatsink

If the actual operating junction temperature is greater than the selected safe operating junction temperature determined in step 3, than a heatsink is required. The junction temperature will be calculated as follows:

$$T_J = P_D (R_{\theta JA} + R_{\theta CS} + R_{\theta SA}) + T_A$$

where $R_{\theta JC}$ is the thermal resistance junction−case,
$R_{\theta CS}$ is the thermal resistance case−heatsink,
$R_{\theta SA}$ is the thermal resistance heatsink−ambient.

If the actual operating temperature is greater than the selected safe operating junction temperature, then a larger heatsink is required.

Some Aspects That can Influence Thermal Design

It should be noted that the package thermal resistance and the junction temperature rise numbers are all approximate, and there are many factors that will affect these numbers, such as PC board size, shape, thickness, physical position, location, board temperature, as well as whether the surrounding air is moving or still.

Other factors are trace width, total printed circuit copper area, copper thickness, single− or double−sided, multilayer board, the amount of solder on the board or even color of the traces.

The size, quantity and spacing of other components on the board can also influence its effectiveness to dissipate the heat.

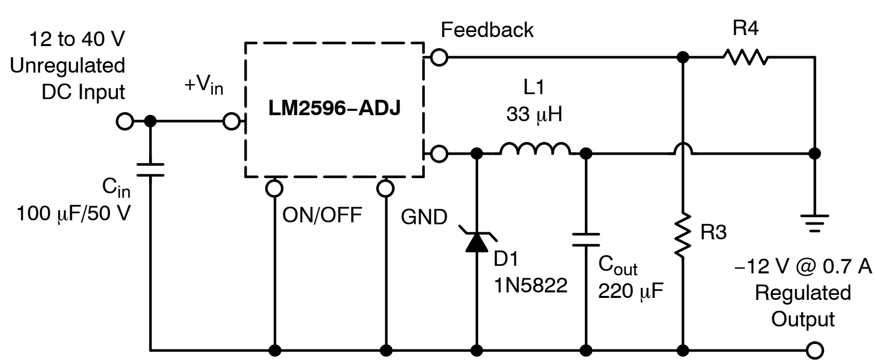

Figure 22. Inverting Buck−Boost Develops −12 V